

### 1, 2 and 3-Channel ESD Arrays in CSP

### **Features**

- Functionally and pin compatible with CMD's CSPESD301/302/303 family of devices
- OptiGuard™ coated for improved reliability at assembly
- 1, 2 or 3 channels of ESD protection
- ±15kV ESD protection (IEC 61000-4-2, contact discharge)
- ±30kV ESD protection (HBM)
- Supports both AC and DC signal applications
- Low leakage current (<100nA)
- Chip Scale Package features extremely low lead inductance for optimum ESD and filter performance
- 4 bump, 1.06 x 0.93mm footprint Chip Scale Package (CSP)
- Lead-free version available

## **Applications**

- I/O port protection
- EMI filtering for data ports
- Cellphones, notebook computers, PDAs
- Wireless Handsets
- MP3 Players
- Digital Still Cameras
- Handheld PCs

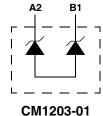
### **Product Description**

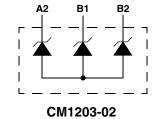
The CM1203 comprises a family of 1, 2, and 3-channel ESD protection arrays, which integrate two, three and four identical avalanche-style diodes. It is intended that one of these diodes is connected to GND and the other diodes provide ESD protection for up to 3 lines depending upon the configuration utilized. The backto-back diode connections provide ESD protection for nodes that have AC signals up to 5.9V peak. These devices provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The diodes are designed and characterized to safely dissipate ESD strikes of ±15kV, well beyond the maximum requirements of the IEC 61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, these devices protect against contact discharges of greater than ±30kV. The diodes also provide some EMI filtering, when used in combination with a PCB trace or series resistor.

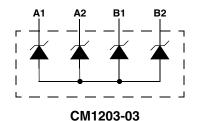
These devices are particularly well-suited for portable electronics (e.g. cellular telephones, PDAs, notebook computers) because of their small package format and easy-to-use pin assignments.

The CM1203 incorporates OptiGuard™ coating which results in improved reliability at assembly. The CM1203 is available in a space-saving, low-profile, chip-scale package with optional lead-free finishing.

#### **Electrical Schematics**

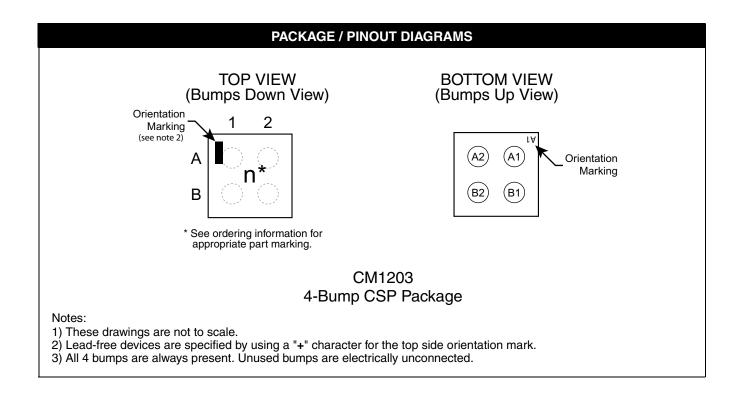






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# **Ordering Information**

	PART NUMBERING INFORMATION						
		Standard Finish		Lead-free Finish <sup>2</sup>			
Bumps	Package	Ordering Part Number <sup>1</sup>	Part Marking	Ordering Part Number <sup>1</sup>	Part Marking		
4	CSP	CM1203-01CS	Р	CM1203-01CP	Р		
4	CSP	CM1203-02CS	Q	CM1203-02CP	Q		
4	CSP	CM1203-03CS	R	CM1203-03CP	R		

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Note 2: Lead-free devices are specified by using a "+" character for the top side orientation mark.



## **Specifications**

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	RATING	UNITS				
Storage Temperature Range	-65 to +150	°C				
DC Package Power Rating	200	mW				

STANDARD OPERATING CONDITIONS					
PARAMETER	RATING	UNITS			
Operating Temperature Range	-40 to +85	°C			

ELECTRICAL OPERATING CHARACTERISTICS <sup>1</sup>								
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS		
V <sub>SO</sub>	Diode Stand-off Voltage	$I_{DIODE} = \pm 10 \mu A$	±5.9			V		
I <sub>LEAK</sub>	Diode Leakage Current	V <sub>IN</sub> =3.3V			100	nA		
V <sub>SIG</sub>	Small Signal Clamp Voltage Positive Clamp Negative Clamp	I <sub>DIODE</sub> = 10mA I <sub>DIODE</sub> = -10mA	6.0 -9.2	7.6 -7.6	9.2 -6.0	V V		
V <sub>ESD</sub>	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2	Notes 2, 3 and 4	±30 ±15			kV kV		
V <sub>CL</sub>	Clamping Voltage during ESD Discharge MIL-STD-883 (Method 3015), 8kV Between adjacent bumps Between diagonal bumps	Notes 2, 3 and 4		19.5 19.9		V V		
R <sub>D</sub>	Dynamic Resistance Between adjacent bumps Between diagonal bumps	Notes 2, 3 and 4		0.85 1.10		$\Omega$		
С	Capacitance	At 0VDC, 1MHz, 30mVAC		27		pF		

Note 1: T<sub>A</sub>=25°C unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to another diode, one at a time.

Note 3: Unused pins are left open.

Note 4: These parameters are guaranteed by design and characterization.

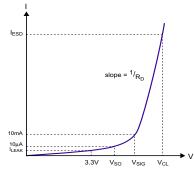


Figure 1. Parameter Legend



### **Performance Information**

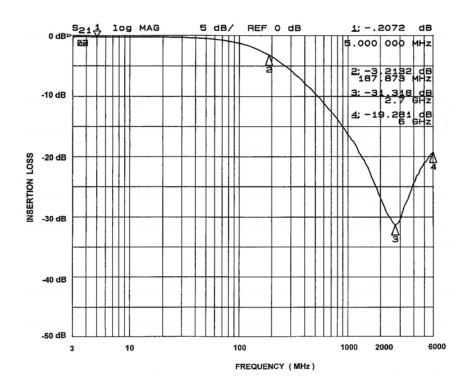


Figure 2. Typical EMI Filter Performance (0VDC, 50 Ohm Environment)

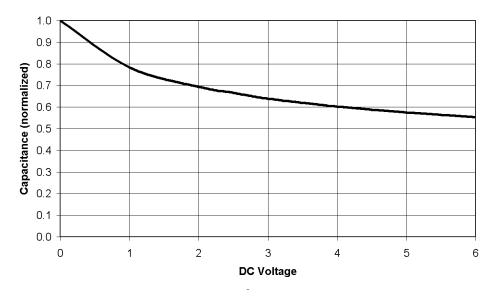


Figure 3. Typical Capacitance vs. Input Voltage (normalized to 0VDC)



## Performance Information (cont'd)

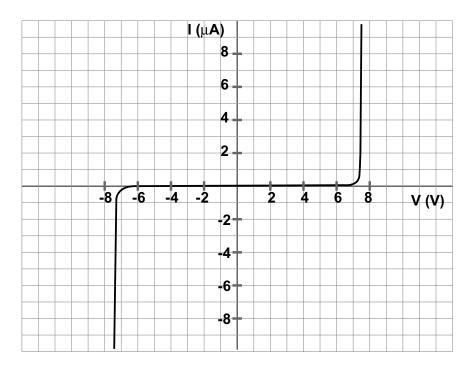


Figure 4. Low Current I-V Curve

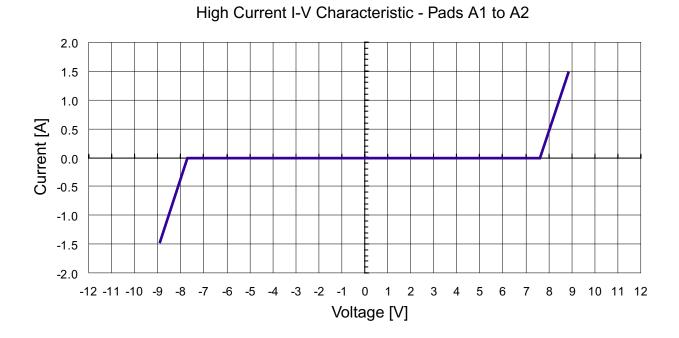


Figure 5. High Current I-V Curve

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## **Application Information**

Refer to Application Note AP-217, "The Chip Scale Package", for a detailed description of Chip Scale Packages offered by California Micro Devices.

PRINTED CIRCUIT BOARD RECOMMENDATIONS					
PARAMETER	VALUE				
Pad Size on PCB	0.275mm				
Pad Shape	Round				
Pad Definition	Non-Solder Mask defined pads				
Solder Mask Opening	0.325mm Round				
Solder Stencil Thickness	0.125mm - 0.150mm				
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.330mm Round				
Solder Flux Ratio	50/50 by volume				
Solder Paste Type	No Clean				
Pad Protective Finish	OSP (Entek Cu Plus 106A)				
Tolerance — Edge To Corner Ball	<u>+</u> 50μm				
Solder Ball Side Coplanarity	<u>+</u> 20μm				
Maximum Dwell Time Above Liquidous	60 seconds				
Soldering Maximum Temperature	260°C				

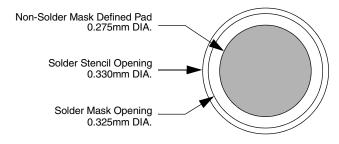


Figure 6. Recommended Non-Solder Mask Defined Pad Illustration

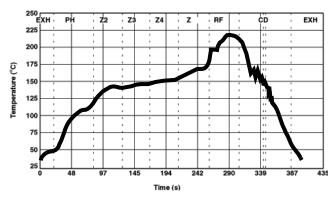


Figure 7. Eutectic (SnPb) Solder **Ball Reflow Profile** 

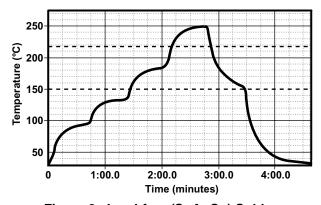


Figure 8. Lead-free (SnAgCu) Solder **Ball Reflow Profile** 

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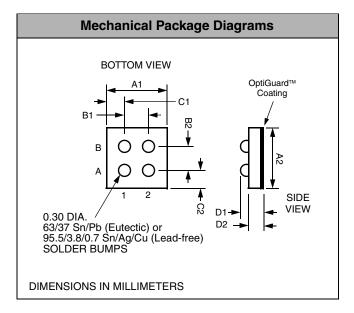


### **Mechanical Details**

### **CSP Mechanical Specifications**

CM1203 devices are packaged in a custom Chip Scale Package (CSP). Dimensions are shown below. For complete information on CSP packaging, see the California Micro Devices CSP Package Information document.

PACKAGE DIMENSIONS							
Pack	age	Custom CSP					
Bum	ıps	4					
Dim	M	lillimete	rs		Inches		
Dilli	Min	Nom	Max	Min	Nom	Max	
A1	0.881	0.925	0.971	0.0347	0.0365	0.0382	
A2	1.015	1.060	1.105	0.0400	0.0417	0.0435	
B1	0.495	0.500	0.505	0.0195	0.0197	0.0199	
B2	0.495	0.500	0.505	0.0195 0.0197 0.0064 0.0084		0.0199	
C1	0.163	0.213	0.263			0.0104	
C2	0.230	0.280	0.330	0.0091	0.0110	0.0130	
D1	0.600	0.670	0.739	0.0236	0.0264	0.0291	
D2	0.394	0.445	0.495	0.0155	0.0175	0.0195	
# per tap		3500 pieces					
Controlling dimension: millimeters							



Package Dimensions for CM1203 Chip Scale Package

#### **CSP Tape and Reel Specifications**

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B <sub>0</sub> X A <sub>0</sub> X K <sub>0</sub>	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P <sub>0</sub>	P <sub>1</sub>
CM1203	1.06 X 0.93 X 0.670	1.14 X 1.00 X 0.70	8mm	178mm (7")	3500	4mm	4mm

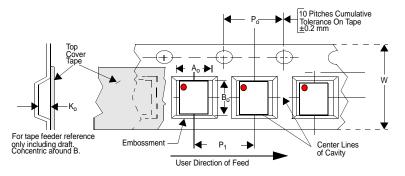


Figure 9. Tape and Reel Mechanical Data

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